

Panasonic Factory Solutions Extends Benefit of 3-in-1 System in Europe

At Productronica 2007, Panasonic Factory Solutions Europe will demonstrate and propose the triune concept of “production equipment,” “production process” and “solution,” which is being promoted by Panasonic Factory Solutions Co., Ltd. in Japan. The company’s theme for this year is “Our Solutions, Your Value.”

Pursues High Cost-Performance

With equipment, Panasonic Factory Solutions Europe will exhibit the CM101 released in Europe in October. The CM101 is a new model, which pursues high performance for cost, while inheriting the concept of the CM Series. It has been developed as a modular placement machine targeted at small- and medium-sized subcontractors that feature small lot production and frequent tooling changes. The company will introduce the

CM101 to Europe for the first time, expanding the base of the CM Series.

The CM101 has a production throughput of 25,000cph thanks to a high-speed 12-nozzle head. With a multi-functional head and high-speed, high-precision recognition system, it achieves high-speed mounting with one beam and one head. Because the machine can be evolved after installation, it achieves advanced process production with minimal initial investment. As it features several module units, it accommodates diverse production formats and various components of up to 140 types. Featuring an excellent compatibility and continuity, the CM101 can be developed into upper-end models of the CM Series in accordance with the expansion in production scale.

At Productronica 2007, Panasonic Factory Solutions Europe will exhibit the CM101 combined with the SP18 screen printing system as a popular-range model line. The SP18 is a popular-range screen printing system specifically designed for surface-mount technology (SMT) production. It enables high-quality printing with simple operation.

The company will also exhibit for reference the RG131, a new guide-pin system radial insertion machine with an insertion pitch of 7.5mm. One platform insertion technology enables improvement in total productivity and reduction of total cost in the audio-video (A/V) industry.

Serves Manufacturing Processes

In terms of production processes, the company



FCX501 ultrasonic flip-chip bonder

will tap the CM602 upper-end high-speed modular mounter designed for large-volume production to introduce various add-on functions that evolve and expand on a single platform. It will promote evolutions that accommodate production process, like expandability and area productivity to accommodate various needs through 3D, substrate warpage recognition, new head, and component supply module, as well as the accommodation to high-quality and high-speed package-on-package (PoP) mounting by controlling substrate height.

Furthermore, it will also demonstrate component checking systems, such as PanaPro and CVT, as well as traceability, material and statistics control software to promote enhanced total efficiency in productivity and quality.

With the aim of backing its track record in the production process field, the company will introduce the supplier award given this year from the world’s largest



CM101 modular placement system



PSX303 plasma cleaning system

automotive electronics manufacturer.

In the microelectronics field, Panasonic Factory Solutions Europe will introduce the FCX501 ultrasonic flip chip bonder designed for the device industry.

The packaging of semiconductor components has shifted from plastic mold package ICs to bare chips that are mounted directly on the substrate and then to flip chips without leads. The FCX501 accommodates flip chip bonding processes widely from the development to mass production.

At Productronica 2007, the company will demonstrate and propose the gold-gold interconnection (GGI) method, a flip chip packaging technology with strong potential demand in Europe.

The company will also display the PSX303 plasma cleaning system, which significantly improves the wire bonding and flip bonding

strength, offering total solution from process to mounting equipment, improved reliability and reduction of total cost.

This year, Panasonic Factory Solutions established a microelectronics technol-

ogy center in Fraunhofer IZM, a world research institution in Munich, Germany, with the aim of accelerating the development of packaging method in Europe. At the event, the company will introduce the functions of the technology center.

Strengthen After Sales Support

With solution, the company will provide thorough support after sales of equipment, regular maintenance program, including the component supply system and feeders, nozzle exchanges and propose upgrading of the machine. It will propose improvement of productivity through diagnosis not only of the mounting process but also of the entire plant.

Panasonic Factory Solutions Europe has a training center in Austria and a wide network in Germany, France, United Kingdom, Spain, Italy, Hungary, Finland, Ireland, Denmark, Switzerland, Turkey, Russia and Tunisia. At Productronica 2007, it will introduce its provision of homogeneous service solutions regardless of region and time, meeting individual customers' needs in the automotive electronics, A/V, electronic manufacturing service (EMS), communication, semiconductor, device, industrial, personal computer and all other industries across Europe. □